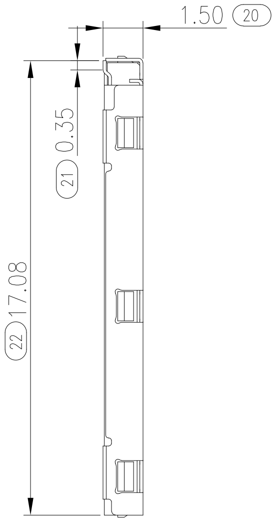
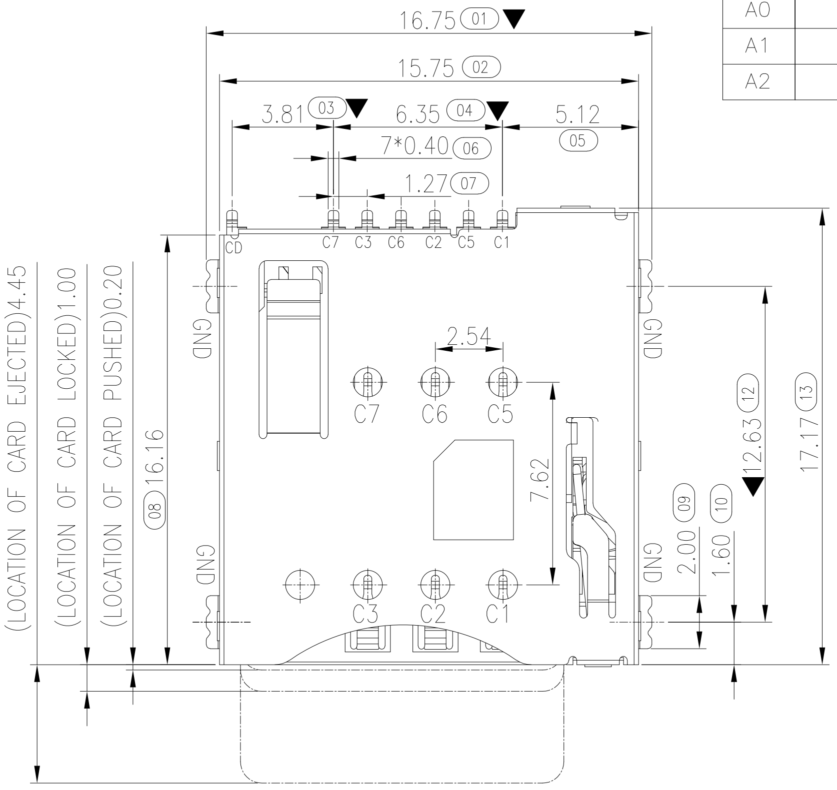
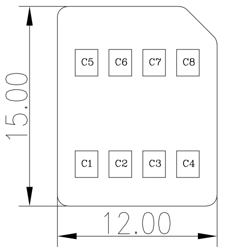
GP Component

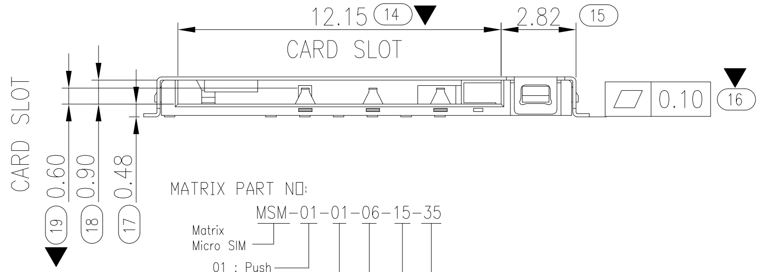
REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2017/05/05	Phebe Su
A1			Change	2018/06/15	Phebe Su
A2			Correct drawing	2019/03/26	Summer Wang

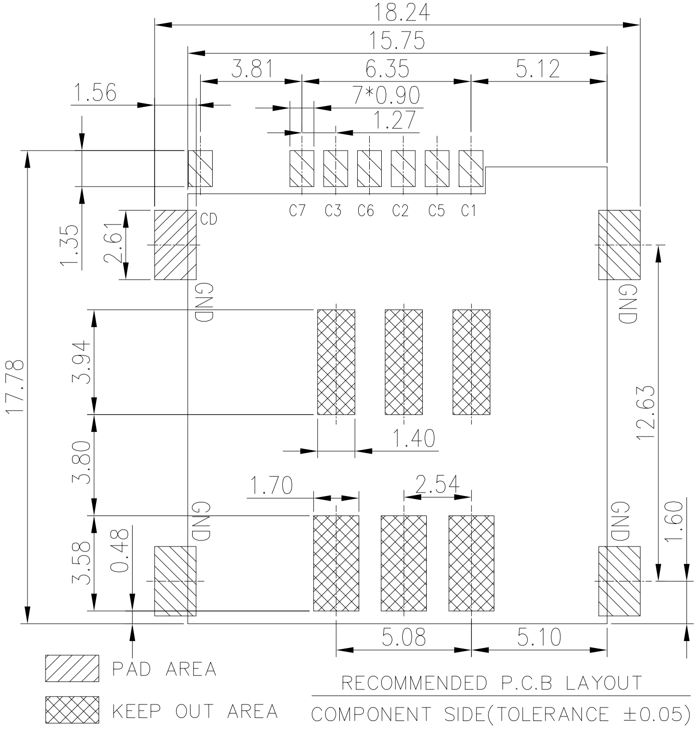




MicroSIM CARD







RECOMMENDED P.C.B LAYOUT

COMPONENT SIDE(TOLERANCE ±0.05)

7	LINK	1PC	STEEL	PLATE WITH NICKEL
6	SPRING	1PC	SWP-B	PLATE WITH NICKEL
5	Slide	1PC	HI-TEMP THERMOPLASTIC	UL94V-0 BLACK
4	Shell	1PC	STEEL	SMT AREA:GOLD PLATED
3	CD Switch	1PC	COPPER ALLOY	CONTACT AREA:GOLD PLATED
2	Data Contact	1PC	COPPER ALLOY	CONTACT AREA:GOLD PLATED
1	Housing	1PC	HI-TEMP THERMOPLASTIC	UL94V-0 BLACK
NO	Description	Dosage	Material	Color/plating

MATRIX PART NO:

MSM-01-01-06-15-35

Matrix Micro SIM

01 : Push
02 : Non-Push

Gold Plating
01:1u"

Pin number
06:6+1pin

Height

Series Number

NOTES:

1. SPECIALITY:
   - 1.1 Rated current:1.0A
   - 1.2 Rated voltage:30V
   - 1.3 Contact Resistance:50mΩ MAX
   - 1.4 Insulation Resistance:1000MΩ MIN 500V DC
   - 1.5 Dielectric withstanding voltage: 500V AC.
   - 1.6 Solder ability:250±5℃，5±0.5s.
   - 1.7 Durability:1500 Cycles Min.
   - 1.8 Operating condition:Temperature-40℃～+85℃；

ELECTRIC FUNCTION	DETECT SWITCH
WITHOUT CARD	CLOSED
CARD INSERTED	OPEN

SWITCH OPERATION DIAGRAM

MicroSIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

Matrix Electronics Co.,Ltd

TOLERANCE: X. X.X ±0.30 X.XX ±0.20 X.XXX ±0.10 ANGLE: ±3°	DESIGN BY : Summer Wang	DATE : 2019/03/26	PART NAME:	Micro SIM PUSH H1.5
	CHECKED BY: Vicky Hsieh	DATE : 2019/03/26	PART NO.	MSM-01-01-06-15-35
	APPROVED BY1: Richard Hsieh	DATE : 2019/03/26	MOLD NO.	NA
UNIT: mm [inch]	APPROVED BY2:	DATE :	DRAW NO.	
SCALE:1:1 SIZE:A4	Richard Hsieh	2019/03/26	SHEET NO.	1 OF 1